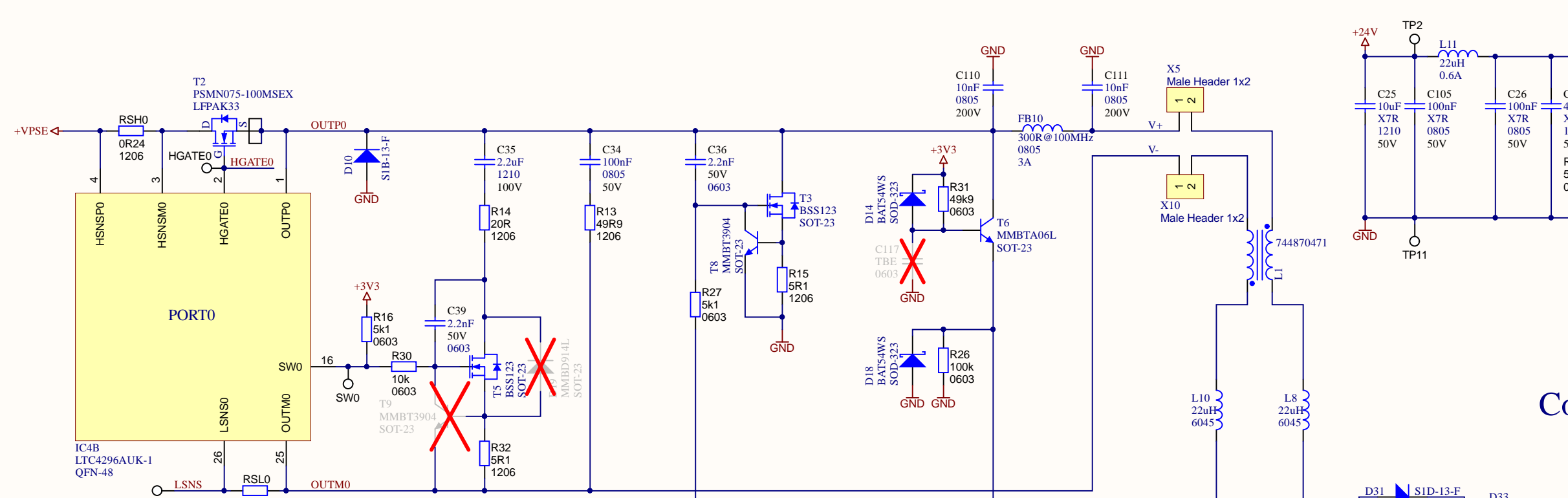
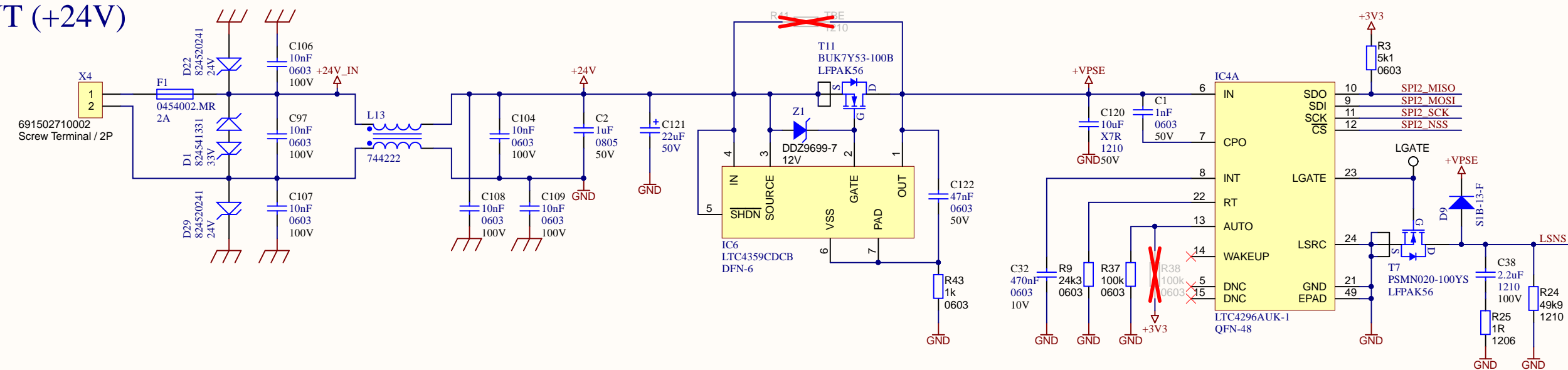
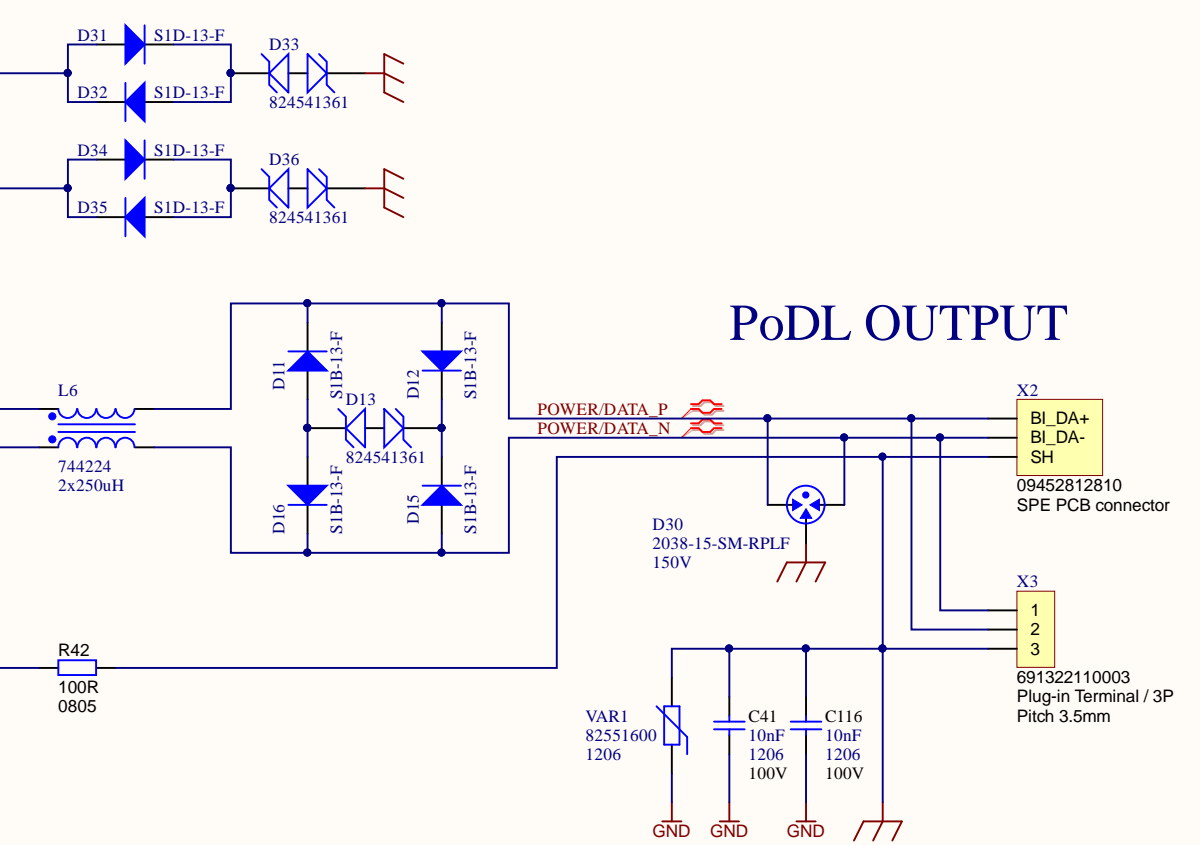
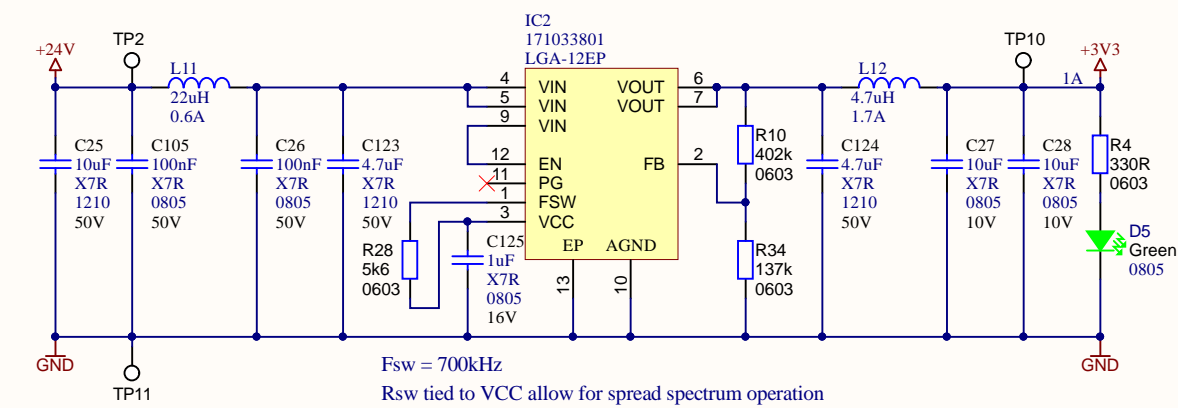


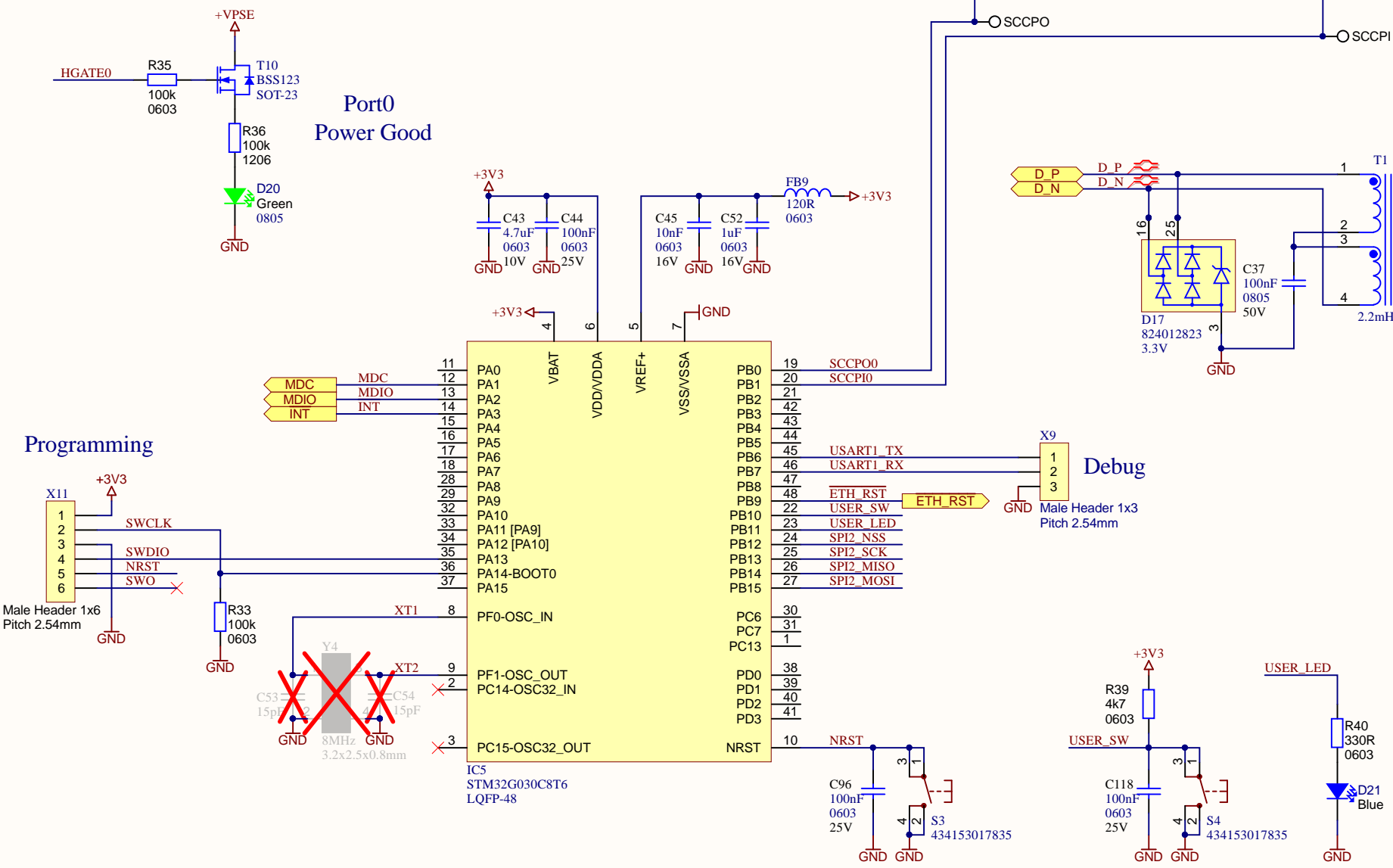
DC INPUT (+24V)



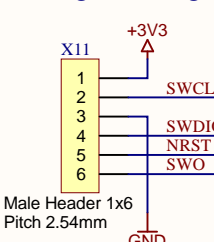
Coupling/Decoupling



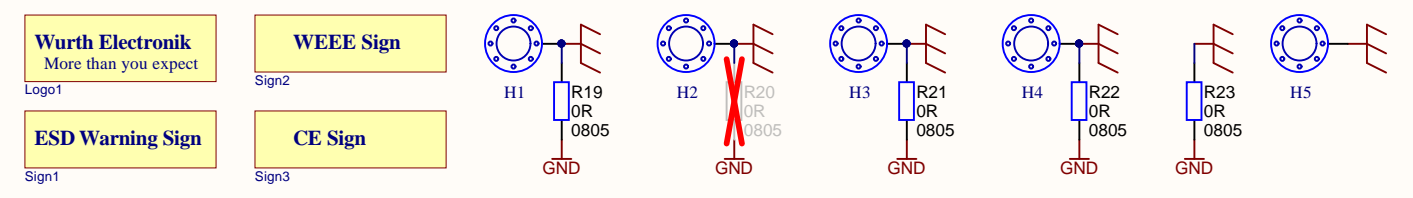
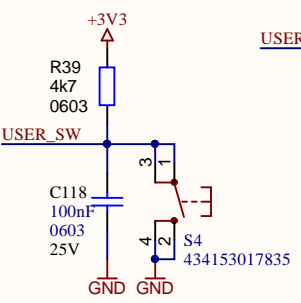
PoDL OUTPUT



Programming

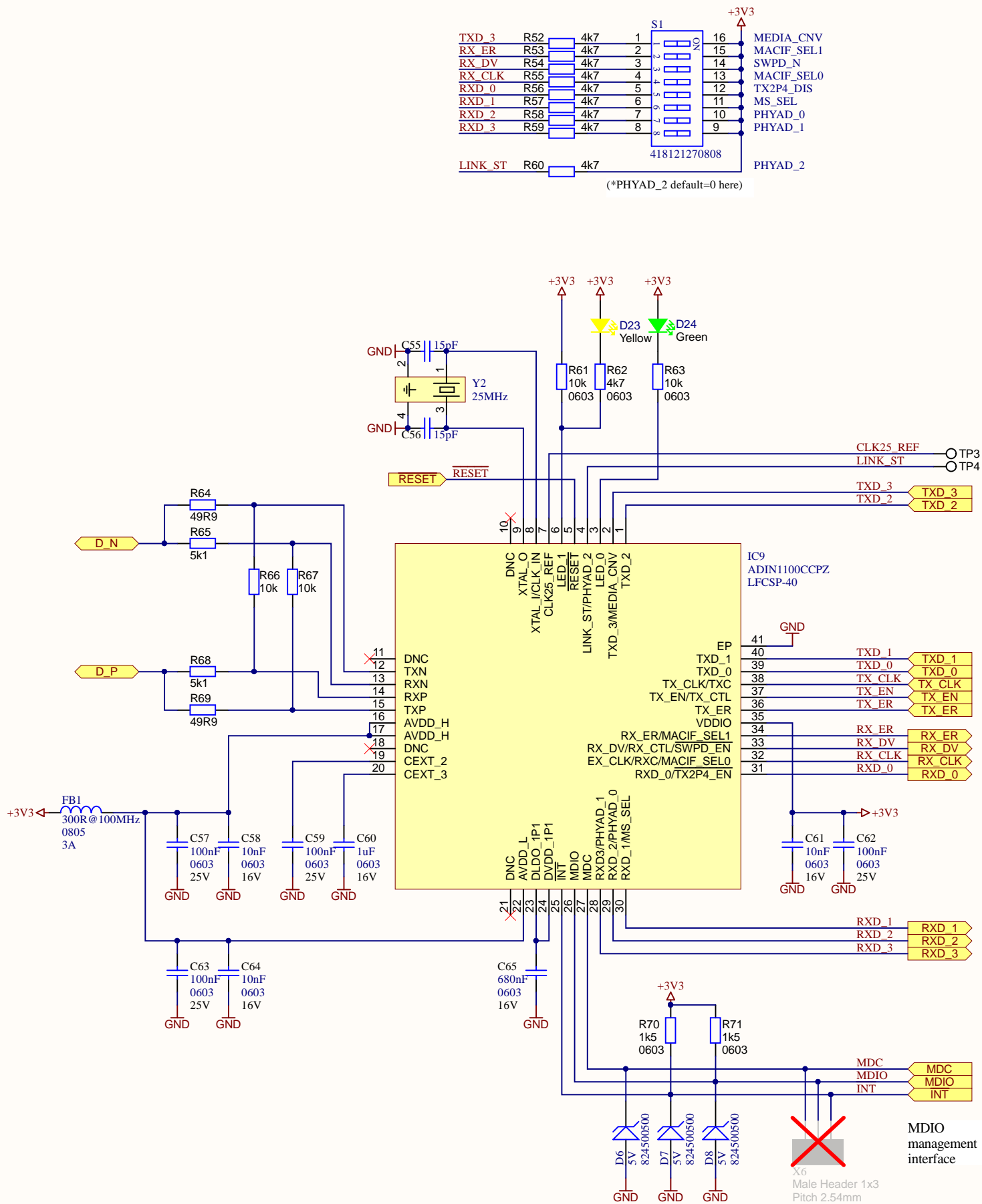


Debug



Rev.	Content	Date	Name	WÜRTH Elektronik eiSos			
1.0	Original Document	09-03-2023	Nattawut	<div> <div>PoDL</div> <div>PSE Port, Power, Controller, MCU</div> <div>Customer:</div> </div> <div> <div>Size A3</div> <div>Document Number 01-PSE_Power_MCU.SchDoc</div> <div>Modified By: Nattawut</div> <div>Rev 1.6</div> </div> <div> <div>Print Date : 16/09/2024</div> <div>Design Date : Thu 9th Mar, 2023</div> <div>Sheet: 1 of 4</div> </div>			
1.1	Change to AD controller	10-05-2023	Nattawut				
1.2	Update Power Coupling	29-10-2023	Nattawut				
1.3	Correct for IC4 unused ports	13-12-2023	Nattawut				
1.4	Improve for EMC ability	14-05-2024	Nattawut				
1.5	Add D36, Replace FB7 to R162	04-07-2024	Nattawut				
1.6	Improve for EMC ability	15-09-2024	Nattawut				

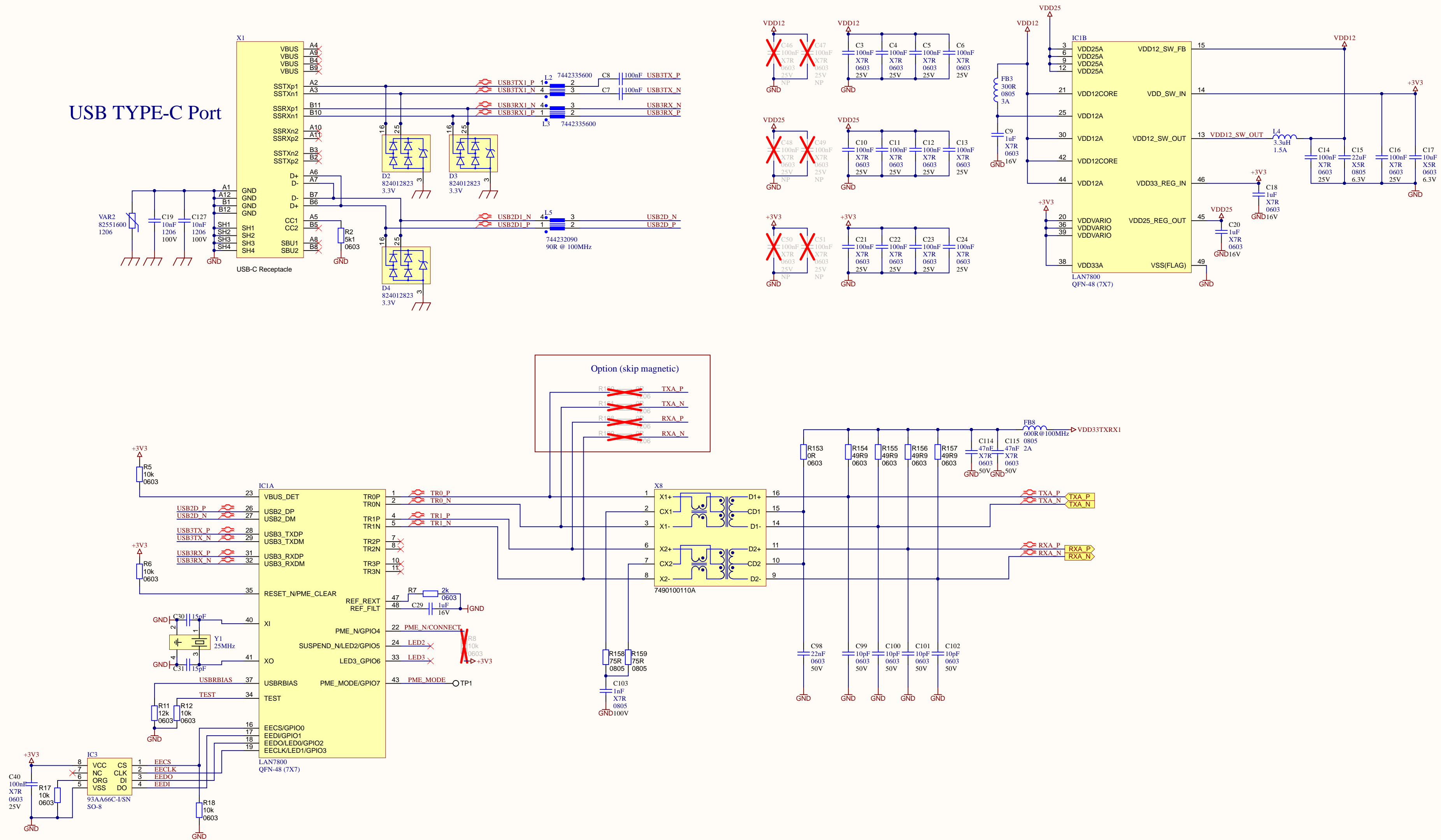
ADIN1100 HARDWARE CONFIGURATION



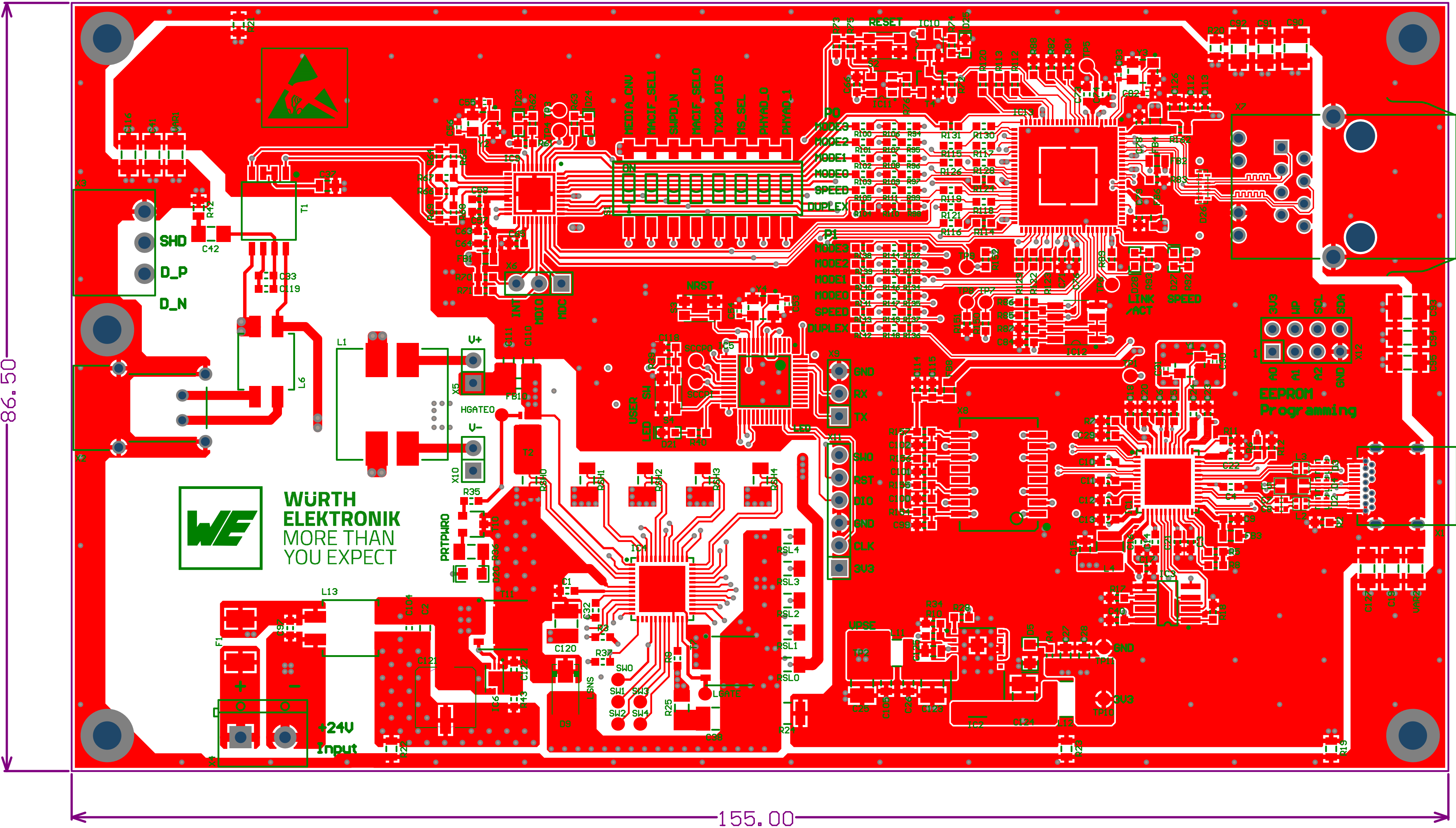
Rev.	Content	Date	Name	WÜRTH Elektronik eiSos			
1.0	Original Document	09-03-2023	Nattawut				
1.1	Change to AD controller	10-05-2023	Nattawut				
1.2	Update Power Coupling	29-10-2023	Nattawut				
1.3	Correct for IC4 unused ports	13-12-2023	Nattawut				
1.4	Improve for EMC ability	14-05-2024	Nattawut				
1.5	Add D36, Replace FB7 to R16	04-07-2024	Nattawut				
1.6	Improve for EMC ability	15-09-2024	Nattawut				

PoDL		Customer:	
ADIN1100 10BASE-T1L PHY			
Size	Document Number	Modified By:	Rev
A3	02-10BASE-T1L_PHY.SchDoc	Nattawut	1.6
Print Date : 16/09/2024		Design Date : Thu 9th Mar, 2023	Sheet: 2 of 4

USB TYPE-C Port

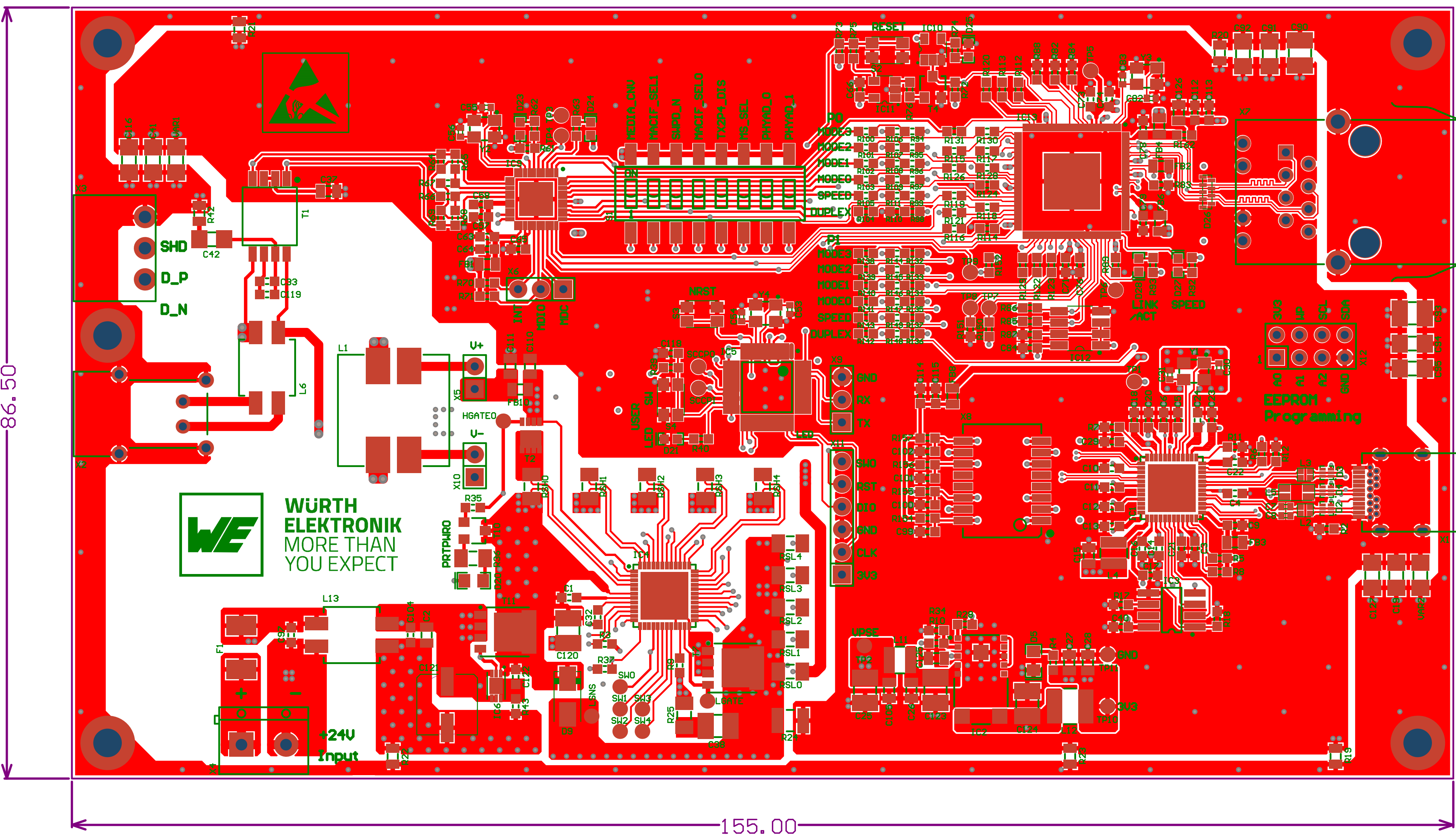


Top Layer



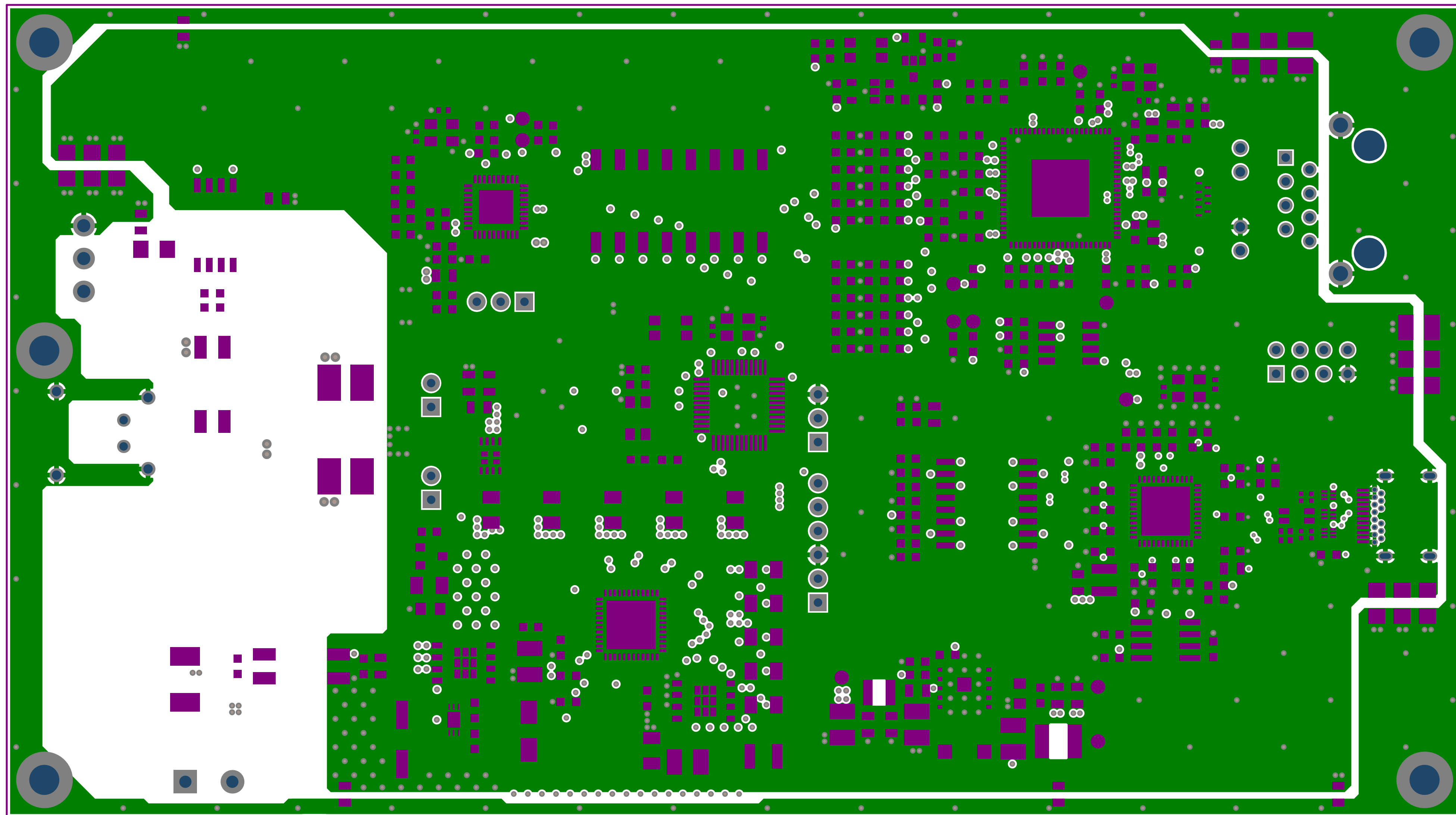
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.8	
3	Top Layer	Copper	0.035mm		
4	Dielectric 1	7628	0.210mm	4.6	
5	Signal Layer 2	Copper	0.015mm		
6	Dielectric 3	Core-009	1.065mm	4.6	
7	Signal Layer 3	Copper	0.015mm		
8	Dielectric 2	PP-006	0.210mm	4.6	
9	Bottom Layer	Copper	0.035mm		
10	Bottom Solder	Solder Resist	0.010mm	3.8	
11	Bottom Overlay				

Top Layer



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.8	
3	Top Layer	Copper	0.035mm		
4	Dielectric 1	7628	0.210mm	4.6	
5	Signal Layer 2	Copper	0.015mm		
6	Dielectric 3	Core-009	1.065mm	4.6	
7	Signal Layer 3	Copper	0.015mm		
8	Dielectric 2	PP-006	0.210mm	4.6	
9	Bottom Layer	Copper	0.035mm		
10	Bottom Solder	Solder Resist	0.010mm	3.8	
11	Bottom Overlay				

Inner Layer2 (GND Plane)



Inner Layer3 (Power/GND Plane)

